L Number	Hits	Search Text	DB	Time stamp
29	10172	((stacked stack) near3(chip semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:15
30	3259	(((stacked stack) near3(chip semiconductor))) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:16
31	2885	((((stacked stack) near3(chip semiconductor))) and lead) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:16
32	14814	((stacked stack) near3 (chip package semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:16
33	4189	(((stacked stack) near3 (chip package semiconductor))) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:16
34	3605	((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:19
35	3278	(((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:20
36	233	((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and (tsop (thin adj small adj outline adj package))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 13:21
37	35	(((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and (tsop (thin adj small adj outline adj package))) and ((chip adj select) (clock adj enable))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:21
38	28	5455740.URPN.	USPAT	2003/03/23 14:34
39	1	6242285.URPN.	USPAT	2003/03/23 14:36
40	52	("Re36229" | "4956694" | "5138438" | "5221642" | "5236117" | "5279029" | "5313096" | "5332922" | "5367766" | "5369056" | "5369058" | "5371866" | "5377077" | "5420751" | "5446620" | "5448450" | "5455740" | "5479318" | "5484959" | "5493476" | "5498906" | "5499160" | "5512783" | "5528075" | "5543664" | "5550711" | "5552963" | "5561591" | "5566051" | "5572065" | "5581121" | "5585668" | "5586009" | "5588205" | "5592364" | "5605592" | "5612570" | "5615475" | "5631193" | "5654877" | "5702985" | "5778522" | "5783464" | "5801437" | "5804870" | "5811877" | "5828125" | "5843807" | "5864175" | "5869353" | "5895232" | "5945732").PN.	USPAT	2003/03/23 14:37
41	4	5778522.URPN.	USPAT	2003/03/23 14:39
42	16	("4103318" | "4932873" | "4956694" | "5057026" | "5236117" | "5279029" | "5279991" | "5281852" | "5367766" | "5394010" | "5475920" | "5499160" | "5514907" | "5523619" | "5543664" | "5592364").PN.	USPAT	2003/03/23 14:40
43	10	5811877.URPN.	USPAT	2003/03/23 14:46
44	6	("4620215" | "5068712" | "5157478" | "5299092" | "5394010" | "5554886").PN.	USPAT	2003/03/23 14:47

45	11	"5512783"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:06
47	5	"6208021"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:11
46	25	"5760471"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:12
48	0	6262476.URPN.	USPAT	2003/03/23 16:16
49	7	("4696525" | "5138438" | "5323060" | "5479318" | "5508563" | "5530292" | "5760471").PN.	USPAT	2003/03/23 16:16
50	0	6213747.URPN.	USPAT	2003/03/23 16:18
51	30	("3404454" | "4682270" | "4778641" | "5095402" | "5172214" | "5200364" | "5214845" | "5331235" | "5418189" | "5436500" | "5466887" | "5471369" | "5475259" | "5483024" | "5486720" | "5493153" | "5498902" | "5508565" | "5519251" | "5527743" | "5530286" | "5530292" | "5535509" | "5554823" | "5554886" | "5570272" | "5572068" | "5679978" | "5760471" | "6007317").PN.	USPAT	2003/03/23 16:18
53	122	((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:35
54	8	(((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) and (straighten$4 flatten$4) and (cut cutting shorten$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:53
55	114	(((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) not (((((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) and (straighten$4 flatten$4) and (cut cutting shorten$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:54
56	81	((((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) not (((((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) and (straighten$4 flatten$4) and (cut cutting shorten$3))) not ((((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and (tsop (thin adj small adj outline adj package))) and ((chip adj select) (clock adj enable)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:54
57	8	5648681.URPN.	USPAT	2003/03/23 16:56
58	3	("5276352" | "5424576" | "5457341").PN.	USPAT	2003/03/23 16:56